PC	Number:	20160712001					PCN Date: 07/14/2016		
Title: Datasheet for TPS2062-Q1/TPS2065-Q1									
Customer Contact:		PCN Manager				Dept:		Quality Services	
Change Type:									
	Assembly Site		Design				Bump Site		
	Assembly Process		Data Sheet			<u> </u>		Vafer Bump Material	
	Assembly Materials			Part number	change			r Bump Process	
	Mechanical Specification			Test Site		Wafer Fab Sit			
	Packing/Shipping/Labeling			Test Process					<u>Aaterials</u>
				water	lafer Fab Process				
Notification Details Description of Change:									
The product datasheet(s) is updated as seen in the change revision history below: Image:									
s De TP:									
http://www.ti.com/lit/ds/symlink/tps2065-q1.pdf									
	son for Change:								
To more accurately reflect device characteristics.									
 Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. Changes to product identification resulting from this PCN: 									
None.									
Product Affected:									
TPS2062QDGNRQ1 TPS2065QDGNRQ1									
For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.									

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com